

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:)	
)	Group Art Unit: 3744
CHEN et al.)	
)	Examiner: Ciric, L.
Application No: 10/712,708)	
)	Docket No:JLINP174/TLC
Filed: November 12, 2003)	
)	Date: Nov. 2, 2007
For: HEAT DISSIPATION MODULE)	
_____)	

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 6, 2006, the term to respond extends to January 8, 2007. Also, this is in response to the Notice of Non-Compliant Amendment dated Oct. 4, 2007, the due date extending to Nov. 4, 2007. Please enter this amendment and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 6 of this paper.

Amendments to the claims are reflected in the listing of claims which begin on page 7 of this paper.

Remarks/Arguments begin on page 11 of this paper.